



## Product Change Notification: BLAS-27GJUK085

### Date:

06-Jun-2025

### Product Category:

32-Bit Microcontrollers

### Notification Subject:

CCB 7046 Final Notice: Qualification of ATP7 as an additional assembly site for selected ATSAM4S16C, ATSAM4S2C, ATSAM4S4C, ATSAM4S8C, ATSAM4SA16C, ATSAM4SD16C and ATSAM4SD32C device families available in 100L TFBGA (9x9x1.2mm) package.

### Affected CPNs:

[BLAS-27GJUK085\\_Affected\\_CPN\\_06062025.pdf](#)

[BLAS-27GJUK085\\_Affected\\_CPN\\_06062025.csv](#)

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of ATP7 as an additional assembly site for selected ATSAM4S16C, ATSAM4S2C, ATSAM4S4C, ATSAM4S8C, ATSAM4SA16C, ATSAM4SD16C and ATSAM4SD32C device families available in 100L TFBGA (9x9x1.2mm) package.

### Pre and Post Summary Changes:

	Pre Change	Post Change	
Assembly Site	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	Amkor Technology Philippines (P3/P4), INC. (ATP7)

<b>Substrate Core Material</b>	CCL-HL832NX	CCL-HL832NX	HL832NXA
<b>Substrate Core Thickness</b>	100±30 UM	100±30 UM	100 UM
<b>Substrate SM Material</b>	AUS308	AUS308	AUS308
<b>Substrate SM Thickness</b>	30+/-15 UM	30+/-15 UM	30+/-10 UM
<b>Wire Material</b>	CuPd	CuPd	CuPdAu
<b>Die Attach Material</b>	2100AS	2100AS	2300
<b>Molding Compound Material</b>	KE-G1250LKDS	KE-G1250LKDS	G770FE
<b>Solder Ball Material</b>	SAC105	SAC105	SAC105

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 30 June 2025 (date code: 2527)

**Note Below EFSD:** Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Timetable Summary:**

	July 2024					>	June 2025				
Work Week	27	28	29	30	31		23	24	25	26	27
<b>Initial PCN Issue Date</b>		x									
<b>Qual Report Availability</b>						x					

Final PCN Issue Date							x				
Estimated Implementation Date											x

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_{PCN}\_Qual\_Report.

**Revision History:**

July 08, 2024: Issued initial notification.

July 11, 2024: Re-issued initial notification. Corrected PCN number.

June 06, 2025: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 30, 2025.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

[PCN\\_BLAS-27GJUK085\\_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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